



Final Product Change Notification

201803030F01

Issue Date: 16-Nov-2018

Effective Date: 14-Feb-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| ☐ Wafer Fab Process | ☒ Assembly Process | ☐ Product Marking | ☐ Test Location | ☐ Design |
| ☐ Wafer Fab Materials | ☐ Assembly Materials | ☒ Mechanical Specification | ☐ Test Process | ☐ Errata |
| ☐ Wafer Fab Location | ☐ Assembly Location | ☐ Packing/Shipping/Labeling | ☐ Test Equipment | ☐ Electrical spec./Test coverage |
| ☐ Firmware | ☒ Other - package case outline in data sheet | | | |

i.MX27 17x17 MAPBGA
Total Max Thickness
Increase From 1.4mm to
1.45mm

Description of Change

NXP Semiconductors announces total max thickness increase from 1.4mm to 1.45mm for the i.MX27 17X17 MAPBGA products listed in the notification, currently assembled at the NXP-ATTJ (NXP, Tianjin, China) Assembly Site. The total max thickness change is due to mold cap target thickness change from 0.7mm to 0.8mm and reflected in an update to the package case outline. Please refer to the attached new datasheet for details.

After PCN implementation, the updated Datasheet MCIMX27EC can be found at:
https://www.nxp.com/products/processors-and-microcontrollers/applications-processors/i.mx-applications-processors/i.mx-mature-processors/multimedia-applications-processors-robust-security-for-mobile-high-performance-connectivity-arm9-core:i.MX27?tab=Documentation_Tab

Reason for Change

The increase of the mold cap target thickness improves process robustness, product quality.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 04-Feb-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no change to product form, function, or reliability. The case outline will be updated to reflect the increased package thickness. Please refer to the new datasheet for details.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 16-Dec-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

MCIMX27VOP4A

MCIMX27VJP4A